

Initial Product/Process Change Notification Document #: IPCN21306X Issue Date: 27 April 2016

Title of Change:	Lead Finish and BOM change for DFN/QFN products assembled at Seremban, Malaysia – Group 2			
Proposed first ship date:	3 September 2016 or earlier upon customer approval			
Contact information:	Contact your local ON Semiconductor Sales Office or <alan.garlington@onsemi.com></alan.garlington@onsemi.com>			
Samples:	Samples will be available after publication of the Final Product Change Notice. Please send any sample requests to <kokinn.hoo@onsemi.com>"</kokinn.hoo@onsemi.com>			
Type of notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.			
	The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>			
Change Part Identification:	Parts can be identified by the marking part number and date code once the Final PCN is published.			
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other			
Change Sub-Category(s): Manufacturing Site Change/A Manufacturing Process Change	Silipping/Fackaging/ivialking			
Sites Affected: All site(s) not ap	plicable			
Description and Purpose:				
This is an advance notice for the next groups of devices which will be converted to use a new Lead Frame using a PPF lead finish along with a new die attach epoxy and mold compound. The Lead Frame will be changing from a Matte Tin lead finish to a PPF finish consisting of Ni-Pd-Au. All new materials will be fully qualified prior to issuing the Final Product Change notice to customers.				
For reference: FPCN # 20948X was issued on 7/10/2015 for the first group of parts with this change.				

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Qualification Plan:

QV DEVICE NAME: NCP1031MNTXG PACKAGE: DFN 8 4*4*1MM 0.8P

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
TC	JESD22-A104	Ta= -65°C to +150°C	1000 сус
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
AC	JESD22 A102	121C,100% RH,15 PSIG	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
RSH	JESD22- B106	Ta = 265C, 10 sec	
SD	JSTD002	Ta = 245C, 10 sec	

Estimated date for qualification completion: 31 March 2016

List of Affected Customer Specific Part:

NOTE: Please be informed that parts impacted by this PDN/PCN are Special/Customer specific parts, thus MPN & CPN info will be available to affected customers only by clicking the "Custom PCN for Selected Company Button" in the Document Analysis page of PCMS/PCN Alert.

List of Affected Standard Parts:

Qualification Vehicle
NCP1031MNTXG

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NCP4304BMNTWG	NCP1031MNTXG
NCP5662MN15R2G	NCP1031MNTXG
NCP5662MN33R2G	NCP1031MNTXG
NCP5662MNADJR2G	NCP1031MNTXG
NCP59151MN50TYG	NCP1031MNTXG
NCP59152MNADJTYG	NCP1031MNTXG
NCS5651MNTXG	NCP1031MNTXG
NCT7491MNTXG	NCP1031MNTXG
NB100LVEP17MNG	NCP1031MNTXG
NB100LVEP17MNR2G	NCP1031MNTXG
NB100LVEP56MNR2G	NCP1031MNTXG
NB100LVEP91MNR2G	NCP1031MNTXG
NB3H83905CMNTXG	NCP1031MNTXG
NB6L295MMNG	NCP1031MNTXG
NB6L295MMNTXG	NCP1031MNTXG

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